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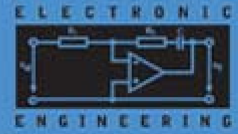

Printed Circuit Boards

DESIGN, FABRICATION, AND ASSEMBLY

- High density interconnects
- CAD/CAM techniques
- Laminates
- Soldering

R. S. Khandpur

PRINTED CIRCUIT BOARDS

Design, Fabrication, Assembly and Testing

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PRINTED CIRCUIT BOARDS

Design, Fabrication, Assembly and Testing

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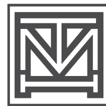

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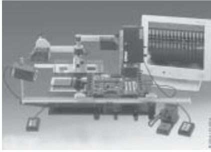

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